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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

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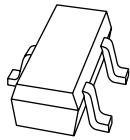
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Kind regards,

Team Nexperia



2PC4617

NPN general-purpose transistor

Rev. 05 — 17 November 2009

Product data sheet

1. Product profile

1.1 General description

NPN transistor in a SOT416 (SC-75) plastic package. The PNP complement is 2PA1774.

1.2 Features

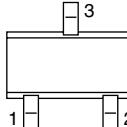
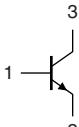
- Low current (max. 150 mA)
- Low voltage (max. 50 V)

1.3 Applications

- General-purpose switching and amplification in communication, Electronic Data Processing (EDP) and consumer applications.

2. Pinning information

Table 1. Pinning

Pin	Description	Simplified outline	Symbol
1	base		
2	emitter		
3	collector		 sym021

3. Ordering information

Table 2. Ordering information

Type number	Package			Version
	Name	Description		
2PC4617Q	SC-75	plastic surface mounted package; 3 leads		SOT416
2PC4617R				
2PC4617S				

4. Marking

Table 3. Marking codes

Type number	Marking code
2PC4617Q	ZQ
2PC4617R	ZR
2PC4617S	ZS

5. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CBO}	collector-base voltage	open emitter	-	60	V
V_{CEO}	collector-emitter voltage	open base	-	50	V
V_{EBO}	emitter-base voltage	open collector	-	7	V
I_C	collector current (DC)		-	150	mA
I_{CM}	peak collector current		-	200	mA
I_{BM}	peak base current		-	200	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25 \text{ }^{\circ}\text{C}$	[1]	-	mW
T_{stg}	storage temperature		-65	+150	$^{\circ}\text{C}$
T_j	junction temperature		-	150	$^{\circ}\text{C}$
T_{amb}	ambient temperature		-65	+150	$^{\circ}\text{C}$

[1] Transistor mounted on an FR4 printed-circuit board, single-sided copper, tin-plated and standard footprint.

6. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient		[1]	-	-	K/W

[1] Transistor mounted on an FR4 printed-circuit board, single-sided copper, tin-plated and standard footprint.

7. Characteristics

Table 6. Characteristics

$T_{amb} = 25^{\circ}\text{C}$; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_{CBO}	collector-base cut-off current	$I_E = 0 \text{ A}; V_{CB} = 30 \text{ V}$	-	-	100	nA
		$I_E = 0 \text{ A}; V_{CB} = 30 \text{ V}; T_j = 150^{\circ}\text{C}$	-	-	5	μA
I_{EBO}	emitter-base cut-off current	$I_C = 0 \text{ A}; V_{EB} = 4 \text{ V}$	-	-	100	nA
h_{FE}	DC current gain	$I_C = 1 \text{ mA}; V_{CE} = 6 \text{ V}$	[1]		120	-
	2PC4617Q		180	-	270	
	2PC4617R		270	-	390	
	2PC4617S				560	
V_{CEsat}	collector-emitter saturation voltage	$I_C = 50 \text{ mA}; I_B = 5 \text{ mA}$	[1]	-	-	mV
C_c	collector capacitance	$I_E = i_e = 0 \text{ A}; V_{CB} = 12 \text{ V}; f = 1 \text{ MHz}$	-	-	1.5	pF
f_T	transition frequency	$I_C = 2 \text{ mA}; V_{CE} = 12 \text{ V}; f = 100 \text{ MHz}$	[1]	100	-	MHz

[1] Pulse test: $t_p \leq 300 \mu\text{s}; \delta \leq 0.02$.

8. Package outline

Plastic surface-mounted package; 3 leads

SOT416

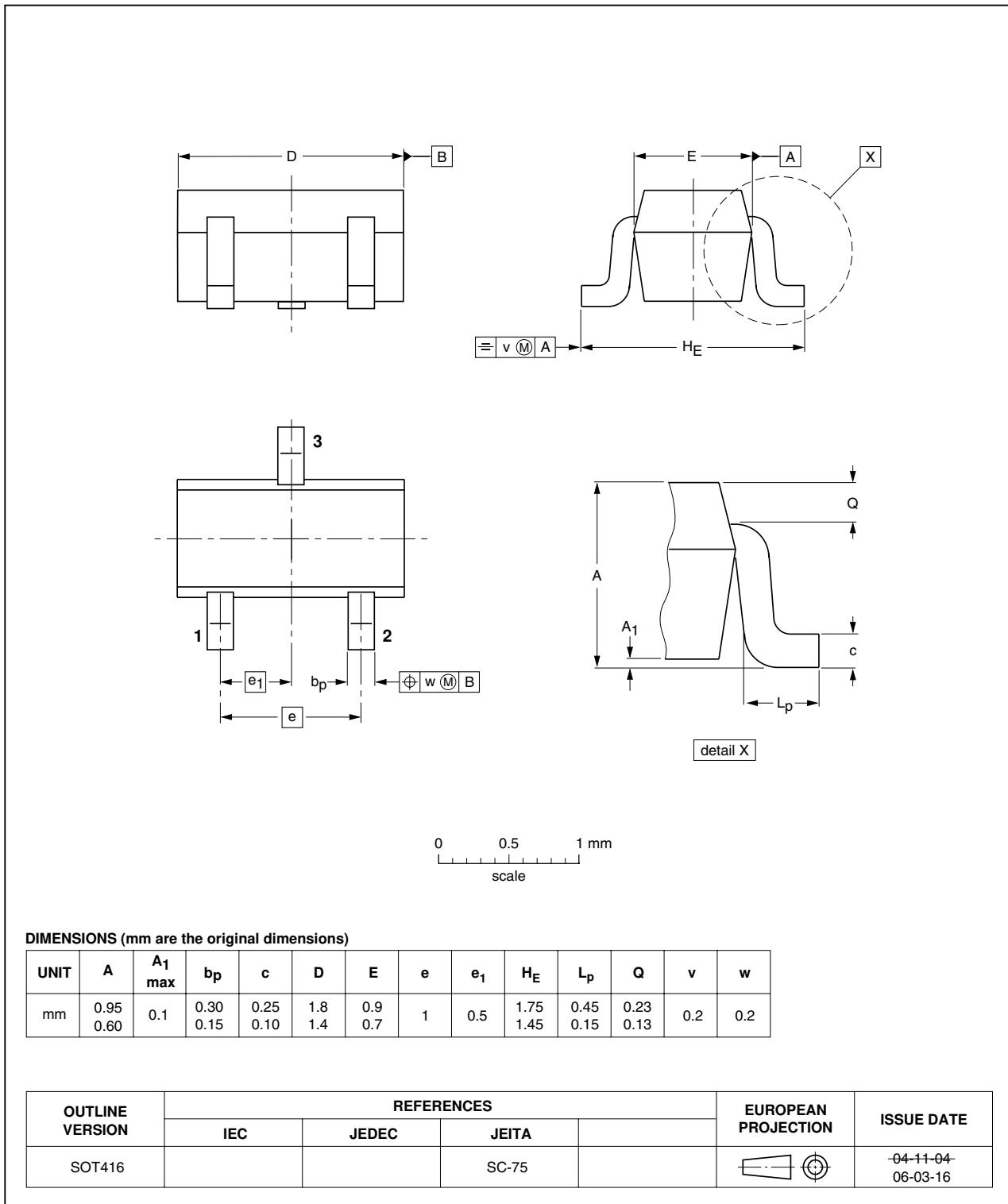


Fig 1. Package outline SOT416 (SC-75)

9. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
2PC4617_5	20091117	Product data sheet	-	2PC4617_4
Modifications:	<ul style="list-style-type: none">This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content.Figure 1 "Package outline SOT416 (SC-75)": updated			
2PC4617_4	20041125	Product data sheet	-	2PC4617_3
2PC4617_3	19990521	Product specification	-	2PC4617_2
2PC4617_2	19980721	Product specification	-	2PC4617_1
2PC4617_1	19970709	Product specification	-	-

10. Legal information

10.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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